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Dear Sirs at the USPTO,

This correspondence is in response to a Restriction Requirement (office action) relating to patent application #10/803,626 from the USPTO; patent examiner Truc T. T. Nguyen: Art Unit 2833: applicant Rapp, Robert J. (Customer # 41400).

The form of my original claims were not ordered such that the patent office could clearly distinguish a single embodiment of my invention, and an initial follow up by myself to the restriction requirement was insufficient. In this response I would like to first identify which of the original claims from this application and present a single embodiment of my invention.

Note: The scope of this response is to respond to the Restriction Requirement such that work on the patent search may proceed. Even though it is not the intent to re-order the claims in this response, I have however provided (at the end of this document) two possible ways that the Claims could be re-ordered that form a Single Embodiment (using the original claim numbers).

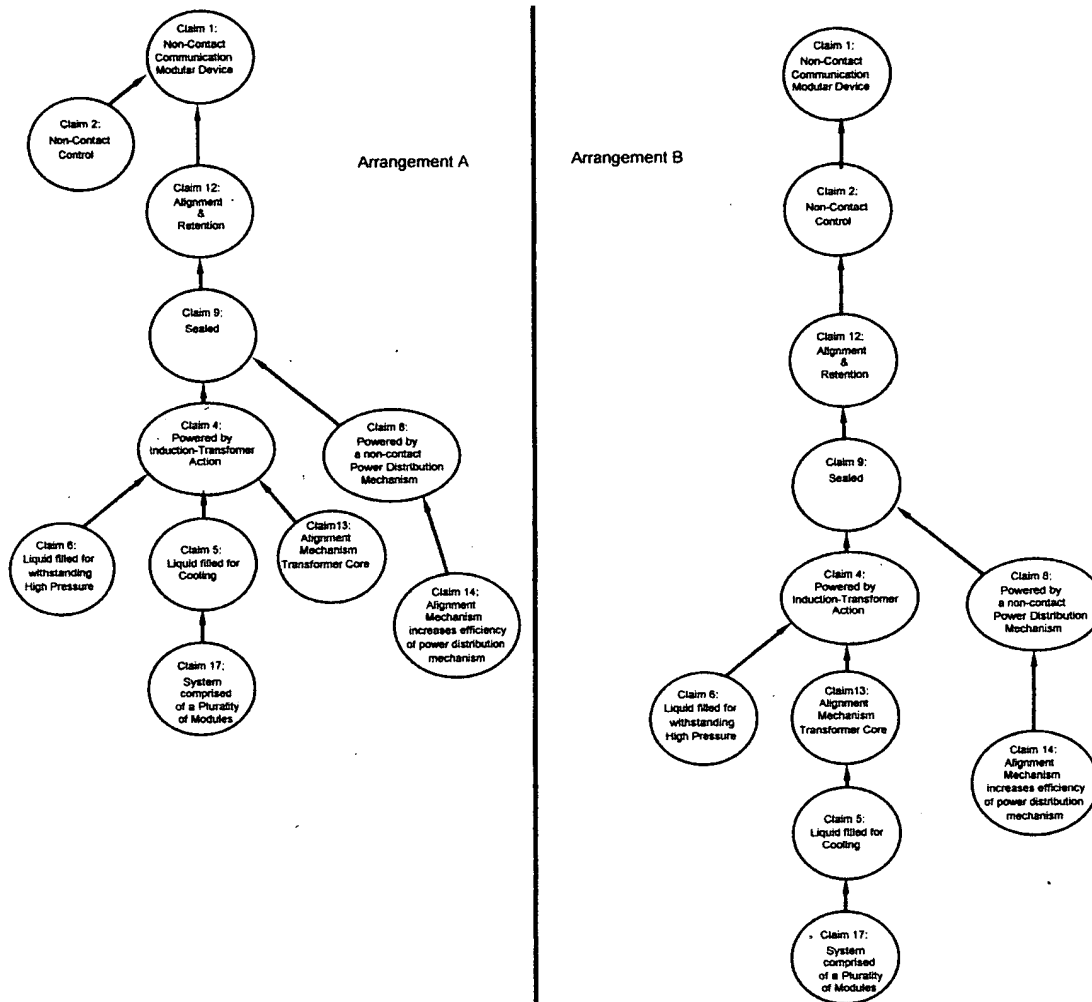
Of the original Claims I would like to retain Claim 1, Claim 2, Claim 4, Claim 5, Claim 6, Claim 8, Claim 9, Claim 12, Claim 13, Claim 14, & Claim 17.

A single embodiment of this invention includes the Claims below, see page 2: (I have listed the claims below retaining the order in my patent application to facilitate easier review of this document as compared to my original patent application, this is not necessarily indicative of how the claims will be ordered, ultimately.)

A single embodiment of this invention includes the Claims below

- Claim 1: {A modular electronic device where non-direct electrical (non-contact) mechanisms are used for inter-module communication, and where modules are attached forming an extendable structure with extendable function.} \*
- Claim 2: {where non-direct contact control mechanisms are used.} \*
- Claim 4: {where inter-module power is distributed using magnetic induction/transformer action.} \*
- Claim 5: {where modules are liquid filled for cooling.} \*
- Claim 9: {where the modules are sealed.} \*
- Claim 12: {where alignment mechanisms are retention mechanisms are used to align and attach modules.} \*
- Claim 13: {where alignment mechanisms are used as a transformer core.} \*
- Claim 17: {A system comprised of a plurality of devices described in Claim 1 and preceding Claims as they comprise a failure resistant extendable methodology for building robust electronic systems.}. \*

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Two possible ways to re-arrange the Claims to form a Single Embodiment

Thank you very much, I look forward to working with the USPTO and am available if there are any issues regarding this document. My phone number is (408) 247-3304, email is [rappri@sbcglobal.net](mailto:rappri@sbcglobal.net), and address is 1120 Ranchero Way #10 San Jose, Ca. 95117. Please send an email if you have difficulty reaching me by phone (I sometimes travel).

Thank you, Robert J. Rapp;  
USPTO Customer # 41400

*Robert J. Rapp*  
3/9/05